

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claims 1-2 (Cancelled)

Claim 3 (Currently amended) A process for producing a multi-layer printed wiring board comprising the steps of:

providing an internal-layer circuit board having an electrical conductor pattern thereon;

providing an inter-laminar adhesive film, which comprises a support film base layer and a layer of a resin composition that is solid at ambient temperature;

laminating said inter-laminar adhesive film to the internal-layer circuit board by contacting the surface of the internal-layer circuit board with the resin composition layer under lamination conditions, including a lamination temperature and pressure, thereby adhering the inter-laminar adhesive film to the surface of the internal-layer circuit board;

wherein said resin composition comprises:

(A) a liquid an epoxy resin; ~~that is liquid at ambient temperature;~~

(B) a polyfunctional epoxy resin with a softening point higher than the lamination temperature and having two or more epoxy groups per epoxy resin molecule; and

(C) a latent epoxy curing agent capable of initiating a reaction at a temperature higher than the lamination temperature.

Claim 4 (Previously presented) The process of claim 3, wherein said resin composition further comprises from 10 to 55% by weight of the composition of a liquid resin other than the liquid

epoxy resin (A) or an organic solvent or a combination thereof.

Claim 5 (Currently amended) A process for producing a multi-layer printed wiring board comprising the steps of:

providing an internal-layer circuit board having an electric conductor pattern thereon;

providing an inter-laminar adhesive film, which comprises a support film base layer and a resin composition that is solid at ambient temperature;

laminating said inter-laminar adhesive film to the internal-layer circuit board by contacting the surface of the internal-layer circuit board with the resin composition layer under laminating conditions, including a lamination temperature and pressure, thereby adhering the inter-laminar adhesive film to the surface of the internal-layer circuit board;

wherein said resin composition comprises:

- (A) a liquid ~~an epoxy resin; that is liquid at ambient temperature;~~
- (B) a polyfunctional epoxy resin with a softening point lower than the lamination temperature and having two or more epoxy groups per epoxy resin molecule;
- (C) a latent epoxy curing agent capable of initiating a reaction at a temperature higher than the lamination temperature; and
- (D) a binder polymer with a weight average molecular weight within a range of 5,000 to 100,000.

Claim 6 (Currently amended) The process of claim 5, wherein said resin composition further comprises from 10 to 55% by weight of a liquid resin other than the liquid epoxy resin (A) or an organic solvent or a combination thereof; and wherein component (D) constitutes from 5 to 50% by weight of the composition.

Claim 7 (Currently amended) The process according to ~~any of claims 1, 2, 3, 4 or 5~~ claim 3, wherein the resin composition further comprises (i) at least one scrubbing component selected from the group consisting of rubber components, amino resins, inorganic fillers, and organic fillers, or (ii) at least one electroless plating catalyst selected from the group consisting of metals, metal compounds and inorganic compositions having metal or metal compounds absorbed or coated thereon, or a combination thereof, wherein the scrubbing component constitutes 5 to 40% by weight of the resin composition, and wherein the said electroless plating catalyst constitutes 0.05 to 3% by weight of the resin composition.

Claim 8 (Currently amended) The process according to ~~any of claims 1, 2, 3, 4 or 5~~ claim 3, wherein said inter-laminar adhesive film comprises a layer of a scrubbable resin composition solid at ambient temperature interposed between said support film base layer and said solid resin composition, wherein said scrubbable resin composition comprises:

- (a) a polyfunctional epoxy resin having two or more epoxy groups per epoxy resin molecule;
- (b) an epoxy curing agent; and
- (c) at least one scrubbing component selected from the group consisting of rubber components, amino resins, inorganic fillers, and organic fillers.

Claim 9 (Previously presented) The process of claim 8, wherein said scrubbable resin composition further comprises an organic solvent.

Claim 10 (Previously presented) The process according to claim 8, wherein said scrubbable resin composition further comprises at least one electroless plating catalyst selected from the group consisting of metals, metal compounds, and inorganic compositions having metal or metal

compounds absorbed or coated thereon.

Claim 11 (Currently amended) The process according to ~~any of claims 1, 2, 3, 4 or 5~~ claim 3, wherein said inter-laminar adhesive film comprises a layer of an additive resin composition solid at ambient temperature interposed between said support film base layer and said solid resin composition, wherein the additive resin composition comprises:

- (a) a polyfunctional epoxy resin having two or more epoxy groups per epoxy resin molecule;
- (b) an epoxy curing agent; and
- (c) at least one electroless plating catalyst selected from the group consisting of metals, metal compounds, and inorganic compositions having metal or metal compounds absorbed or coated thereon.

Claim 12 (Currently amended) The process according to ~~any of claims 1, 2, 3, 4 or 5~~ claim 3, wherein said process further comprises:

- (i) peeling off the support base film layer and optionally thermally curing the resin composition subsequent to laminating the inter-laminar adhesive film, and
- (ii) laminating a copper foil on the optionally thermally cured adhesive layer by the use of heat or adhesive.

Claim 13 (Currently amended) The process according to ~~any of claims 1, 2, 3, 4 or 5~~ claim 3, wherein said lamination conditions are selected from temperatures for contact bonding in the range of from 70 to 200°C, pressure in the range of from 1 to 10 kgf/cm<sup>2</sup> and reduced pressures of 1 to 20 mmHg.

Claim 14 (Previously presented) The process according to claim 13, wherein said process

further comprises:

- (i) peeling off the support base film and optionally, thermally curing the resin composition subsequent to laminating the inter-laminar adhesive film; and
- (ii) laminating a copper foil on the optionally thermally cured adhesive layer by the use of heat or adhesive.

Claim 15 (Currently amended) The process according to ~~any of claims 1, 2, 3, 4 or 5~~ claim 3, wherein said process further comprises:

- (i) peeling off the support base film and optionally thermally curing the resin composition subsequent to laminating the inter-laminar adhesive film;
- (ii) piercing the optionally cured resin composition by means of laser or drill;
- (iii) scrubbing the surface of the optionally cured resin composition by a dry process and optionally, a wet process; and
- (iv) forming a conductor layer as an upper layer thereof by dry plating and optionally wet plating.

Claim 16 (Currently amended) The process according to ~~claim 15~~ 13, wherein said process further comprises:

- (i) peeling off the support base film and optionally, thermally curing the resin composition subsequent to laminating the inter-laminar adhesive film;
- (ii) piercing the optionally cured resin composition by means of laser or drill;
- (iii) scrubbing the surface of the optionally cured resin composition by a dry process and optionally a wet process; and

(iv) forming a conductor layer as an upper layer thereof by dry plating and optionally wet plating.

Claims 17-18 (Cancelled)

Claim 19 (Previously presented) A multi-layer printed wiring board produced by the process of claim 3.

Claim 20 (Previously presented) A multi-layer printed wiring board produced by the process of claim 4.

Claim 21 (Previously presented) A multi-layer printed wiring board produced by the process of claim 5.

Claim 22 (Previously presented) A multi-layer printed wiring board produced by the process of claim 8.

Claim 23 (Previously presented) A multi-layer printed wiring board produced by the process of claim 11.

Claim 24 (Previously presented) A multi-layer printed wiring board produced by the process of claim 12.

Claim 25 (Previously presented) A multi-layer printed wiring board produced by the process of claim 13.

Claim 26 (Previously presented) A multi-layer printed wiring board produced by the process of claim 15.

Claim 27 (Cancelled)

## **Add New Claims**

Claim 28 (New) The process of claim 3, wherein the lamination is carried out by vacuum laminator.

Claim 29 (New) The process of claim 3, wherein the lamination is carried out together with filling the resin composition in a superficial via holes and/or through-holes.

Claim 30 (New) The process of claim 3, wherein the lamination is carried out together with filling the resin composition in a superficial via holes and/or through-holes by vacuum laminator.

Claim 31 (New) The process of claim 3, wherein said resin composition further comprises from 10 to 55% by weight of the composition of a liquid resin other than the liquid epoxy resin (A) or an organic solvent or a combination thereof, and the lamination is carried out by vacuum laminator.

Claim 32 (New) The process of claim 3, wherein said resin composition further comprises from 10 to 55% by weight of the composition of a liquid resin other than the liquid epoxy resin (A) or an organic solvent or a combination thereof, and the lamination is carried out together with filling the resin composition in a superficial via holes and/or through-holes.

Claim 33 (New) The process of claim 3, wherein said resin composition further comprises from 10 to 55% by weight of the composition of a liquid resin other than the liquid epoxy resin (A) or an organic solvent or a combination thereof, the lamination is carried out together with filling the resin composition in a superficial via holes and/or through-holes by vacuum laminator.

Claim 34 (New) The process of claim 5, wherein the lamination is carried out by vacuum

laminator.

Claim 35 (New) The process of claim 5, wherein the lamination is carried out together with filling the resin composition in a superficial via holes and/or through-holes.

Claim 36 (New) The process of claim 5, wherein the lamination is carried out together with filling the resin composition in a superficial via holes and/or through-holes by vacuum laminator.

Claim 37 (New) The process of claim 5, wherein said resin composition further comprises from 10 to 55% by weight of the composition of a liquid resin other than the liquid epoxy resin (A) or an organic solvent or a combination thereof, and the lamination is carried out by vacuum laminator.

Claim 38 (New) The process of claim 5, wherein said resin composition further comprises from 10 to 55% by weight of the composition of a liquid resin other than the liquid epoxy resin (A) or an organic solvent or a combination thereof, and the lamination is carried out together with filling the resin composition in a superficial via holes and/or through-holes.

Claim 39 (New) The process of claim 5, wherein said resin composition further comprises from 10 to 55% by weight of the composition of a liquid resin other than the liquid epoxy resin (A) or an organic solvent or a combination thereof, the lamination is carried out together with filling the resin composition in a superficial via holes and/or through-holes by vacuum laminator.

Claim 40 (New) A multi-layer printed wiring board produced by the process of claim 6.